



Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 57385

Application ID: 10698222



Title of Invention: NON-CONTACT METHODS FOR  
MEASURING ELECTRICAL  
THICKNESS AND DETERMINING  
NITROGEN CONTENT OF  
INSULATING FILMS

First Named Inventor: Jianou Shi

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-10-31

Effective Receipt Date: 2004-03-18

Submission Type: Information Disclosure  
Statement

Filing Type:

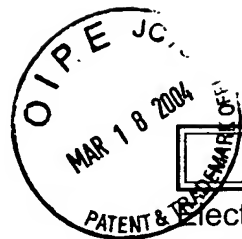
Confirmation number: 1492

Attorney Docket Number: 5589-06800

Total Fees Authorized:

Digital Certificate Holder: cn=Kevin L. Daffer,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US

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**TRANSMITTAL**

Electronic Version v1.1  
Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>NON-CONTACT METHODS FOR MEASURING ELECTRICAL THICKNESS AND DETERMINING NITROGEN CONTENT OF INSULATING FILMS</b>									
Application Number: 10/698222 										
Date: 2003-10-31										
First Named Applicant: Jianou Shi										
Confirmation Number: 1492										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Kevin L. Daffer Registered Number: 34146</td><td>Kevin L. Daffer</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Kevin L. Daffer Registered Number: 34146	Kevin L. Daffer	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Kevin L. Daffer Registered Number: 34146	Kevin L. Daffer	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>5589-06800_IDS-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	5589-06800_IDS-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	5589-06800_IDS-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
<b>Comments</b>										



# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

NON-CONTACT METHODS FOR MEASURING  
ELECTRICAL THICKNESS AND DETERMINING  
NITROGEN CONTENT OF INSULATING FILMS

Application Number: 10/698222



Confirmation Number: 1492

First Named Applicant: Jianou Shi

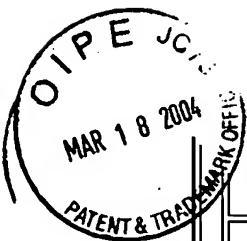
Attorney Docket Number: 5589-06800

Search string: ( 4015203 or 5767691 or 5485091 or 6097196  
or 6202029 or 5594247 or 5644223 or 5767693  
or 4599558 or 4812756 or 5650731 or 5661408  
or 5742658 or 5852232 or 5866806 or 5948972  
or 5955661 or 6011404 or 6191605 or 6267005  
or 5773989 or 6569691 or 3495269 or 3496352  
or 4734721 or 5834941 or 6060709 or 6072320  
or 6091257 or 6104206 or 6121783 or 6201999  
or 6224638 or 20020090746 ).pn.

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4015203	1977-03-29	Verkuil			
	2	5767691	1998-06-16	Verkuil			
	3	5485091	1996-01-16	Verkuil			
	4	6097196	2000-08-01	Verkuil et al.			
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	9	4599558	1986-07-08	Castellano et al.			
	10	4812756	1989-03-14	Curtis et al.			
	11	5650731	1997-07-22	Fung			
	12	5661408	1997-08-26	Kamieniecki et al.			



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	14	5852232	1998-12-22	Samsavar et al.
	15	5866806	1999-02-02	Samsavar et al.
	16	5948972	1999-09-07	Samsavar et al.
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	18	6011404	2000-01-04	Ma et al.
	19	6191605	2001-02-20	Miller et al.
	20	6267005	2001-07-31	Samsavar et al.
	21	5773989	1998-06-30	Edelman et al.
	22	6569691	2003-05-27	Jastrzebski et al.
	23	3495269	1970-02-10	Mutschler et al.
	24	3496352	1970-02-17	Jugle
	25	4734721	1988-03-29	Boyer et al.
	26	5834941	1998-11-10	Verkuil
	27	6060709	2000-05-09	Verkuil et al.
	28	6072320	2000-06-06	Verkuil
	29	6091257	2000-07-18	Verkuil et al.
	30	6104206	2000-08-15	Verkuil
	31	6121783	2000-09-19	Horner et al.
	32	6201999	2001-03-13	Jevtic
	33	6224638	2001-05-01	Jevtic et al.

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020090746	2002-07-11	Xu et al.			

Signature

Examiner Name	Date